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1. Features



Schematic

- Pin Configuration
 1. Anode
 2. Cathode
 3. Emitter
 4. Collector

2. Description

-10

4-

3.Applications

4. Absolute Maximum Rati	ngs (Ta=25
	60
	125
	6
	100
	0
	7
	50
	150
·	250
*1	5000
	-55 + 110
	-55 + 125
*2	260

. . 40 60% . . 1, 2 3, 4

* 2 10



5. Electrical Optical Characteristics at Ta=25°C

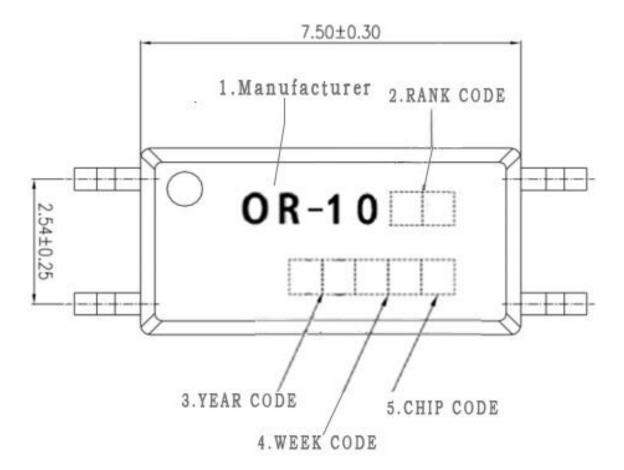
					1	
		50		1.25	1.6	
		4			10	
		0, 1		50		
		20 ,		10	100	
		1 0	0			
		0.1	7			
		5	50		600	%
		5	2.5		30	
	()	10 1			0.3	
		500 40 60%	1012			
		0, 1		0.3		
		5,		3	1	
		100		4.7	1	



6. Rank Table of Current Transfer Ratio



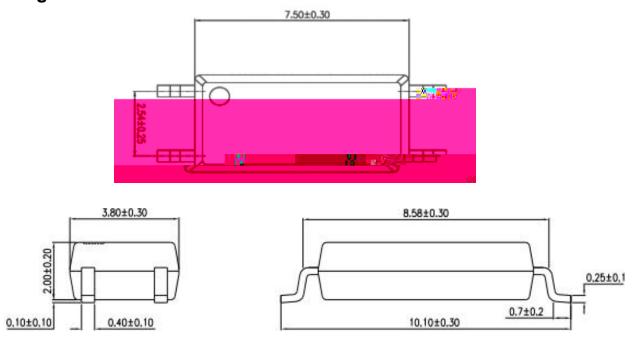
7.Naming Rule



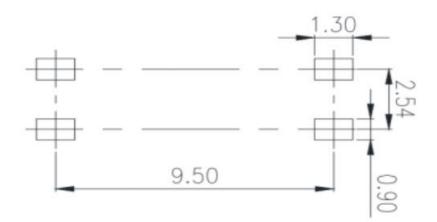




8. Package Dimension

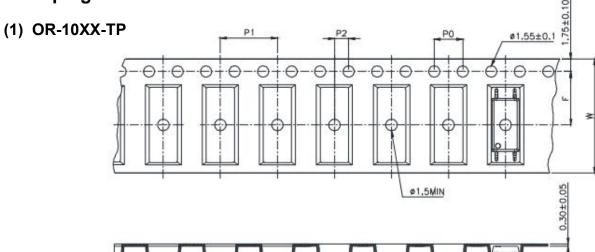


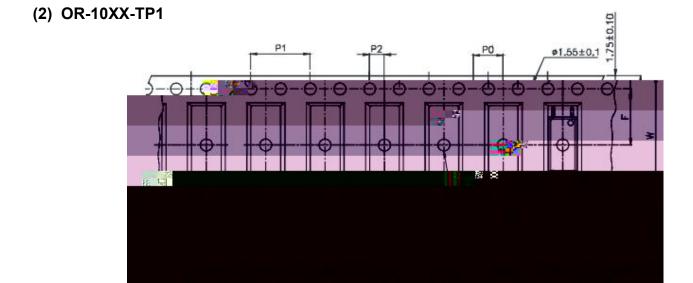
9.RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)





Taping Dimensions



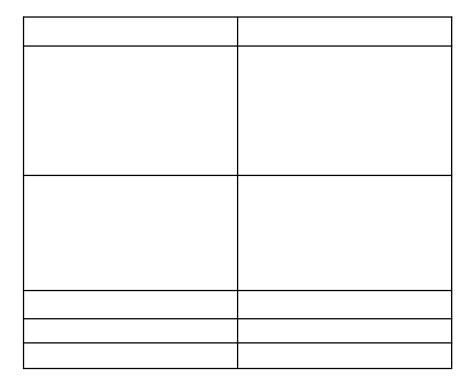


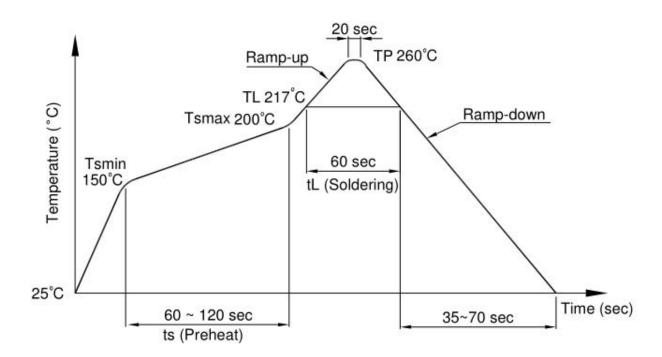
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11.Temperature Profile Of Soldering

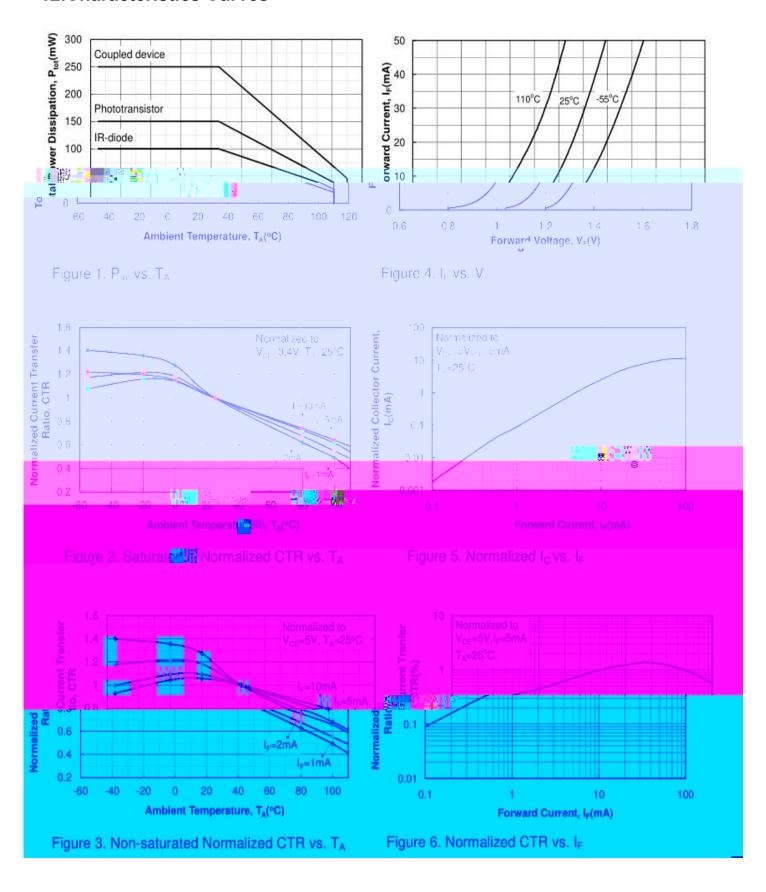
(1).IR Reflow soldering (JEDEC-STD-020C compliant)



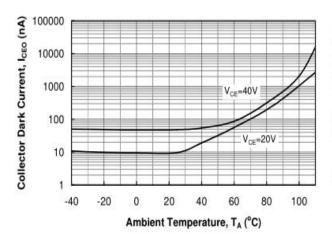




12. Characteristics Curves







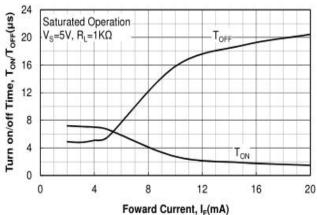
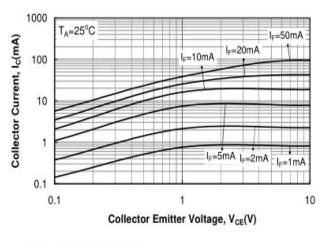


Figure 7. I_{CEO} vs. T_A

Figure 10. Ton / Toff vs. If



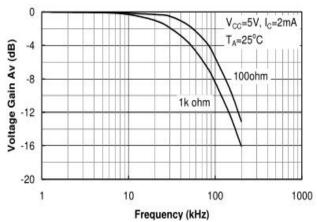


Figure 8. I_C vs. V_{CE}

Figure 11. Frequency Response

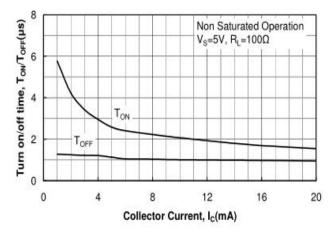


Figure 9. $T_{\text{ON}}\,/\,T_{\text{OFF}}\,\text{vs.}\,\,I_{\text{C}}$



► Notes: